Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.129”**

**PAD FUNCTIONS:**

1. **V IN (2 bond pads)**
2. **V OUT (2 bond pads)**
3. **V OUT SENSE**
4. **ADJUST**

****

**Top Material: Al**

**Backside Material: Ti/Ni/Ag**

**Bond Pad Size: .009 X .00” min.**

**Backside Potential: Ground**

**Mask Ref:**

**APPROVED BY: KW DIE SIZE .055 X .075” DATE: 2/7/23**

**MFG: SILICON SUPPLIES THICKNESS: .011” P/N: 7806AC**

**DG 10.1.2**

#### Rev B, 7/19/02